

ABSTRACT

A probe device including a circuit board for inspection having a great number of inspection electrodes, a probe card having a circuit board for connection having a great number of terminal electrodes and a contact member, an anisotropically conductive connector arranged between the circuit board for inspection and the circuit board for connection and electrically connecting the respective inspection electrodes to the respective terminal electrodes, and a parallelism adjusting mechanism for adjusting a parallelism of the circuit board for inspection and the circuit board for connection to the wafer. The parallelism adjusting mechanism includes a location-varying mechanism, which relatively displaces the circuit board for inspection or the circuit board for connection in the thickness-wise direction of the anisotropically conductive connector. A wafer inspection apparatus can include the probe device.